

Patent Abstracts of Japan

PUBLICATION NUMBER : 06164149
 PUBLICATION DATE : 10-06-94

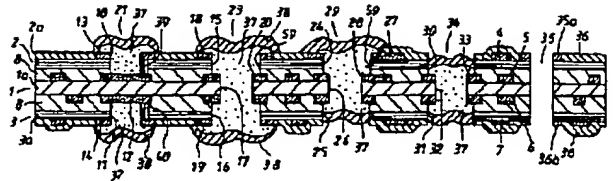
APPLICATION DATE : 17-05-93
 APPLICATION NUMBER : 05139034

APPLICANT : CMK CORP;

INVENTOR : TAKAHASHI KOZO;

INT.CL. : H05K 3/46 H05K 3/40

TITLE : MANUFACTURE OF MULTILAYER
 PRINTED WIRING BOARD



ABSTRACT : PURPOSE: To improve continuity in a multilayer printed circuit board with good efficiency in manufacturing, by removing an insulating layer on an inner part of a land at a laminated outer-layer board on an inner-layer board.

CONSTITUTION: An inner-layer board 1 includes a both-sided copper-clad laminated board with each copper foil laminated inside an insulating layer 1a. Printed wiring circuits 5 and 6 in a given pattern are formed on both sides of the laminated board 1, and through holes 17, 26 and 32 are drilled at lands 20, 28 and 33. Then, single-sided copper-clad laminated boards, each having copper foil laminated at an insulating layer 2a or 3a, are used as outer-layer boards 2 and 3, and bonded on both sides of the inner-layer board 1. The single-sided copper-clad laminated boards are etched so as to form printed wiring circuits 4 and 7 in a given pattern. The insulating layers 2a and 3a on the outer boards 2 and 3 are chemically removed to form contact holes 15, 16, 24, 25, 30 and 31, and these contact holes and the through holes 17, 26 and 32 are filled with a conductive paste 37 so that each given circuit in the inner-layer board or outer-layer board is electrically connected.

COPYRIGHT: (C)1994,JPO&Japio